

**AMENDMENTS TO THE CLAIMS:**

Please replace all prior listings of claims with that which appears below, in which Claims 2, 4, 5, 6, 10-14 and 17 have been cancelled without prejudice or disclaimer of that which is defined thereby, Claims 19-25 have been added and Claims 1, 3, 7, 8, 9, 15, 16 and 18 have been amended to read as follows:

1. (Currently Amended) A lead free soldering ~~Soldering~~ material ~~comprising an alloy~~ consisting essentially of Sn (tin), 10 wt.% or less Ag (silver), ~~10 wt.% or less~~ Bi (bismuth), 1 to 3 ~~10 wt.% or less~~ Sb (antimony), 3 wt.% or less Cu (copper), and 1.0 wt.% or less Ni (nickel), wherein the Sb:Bi wt.% ratio is from 1:1.5-3.

2. (Cancelled)

3. (Currently Amended) Soldering material according to Claim 1 ~~wherein the alloy comprises~~ consisting essentially of 2 to 5 wt.% Ag, 1 to 3 wt.% Bi, 1 to 3 wt.% Sb, 0.5 to 1.5 wt.% Cu and 0.05 to 0.3 wt.% Ni.

4-6. (Cancelled)

7. (Currently Amended) Soldering material according to Claim 1 wherein ~~in the alloy~~ there exists a ratio Sb:Bi of 1:1.5 to 3, based on the weight of Sb and Bi.

8. (Currently Amended) Soldering material according to Claim 7  
~~wherein the alloy exhibits~~ having a Ni-content of 0.05 to 0.2  
wt.%.

9. (Currently Amended) Soldering material according to Claim 1  
wherein ~~the alloy~~ the soldering material is SnAg3.3-4.7Cu0.3-  
1.7Bi2Sb1Ni0.2.

10-14. (Cancelled)

15. (Currently Amended) Soldering material according to Claim 3  
wherein ~~in the alloy~~ there exists a ratio Sb:Bi of 1:1.5 to 3,  
based on the weight of Sb and Bi.

16-17. (Cancelled)

18. (Currently Amended) Soldering material according to Claim 6  
wherein ~~in the alloy~~ there exists a ratio Sb:Bi of 1:1.5 to 3,  
based on the weight of Sb and Bi.

19. (New) A solder joint formed from the lead free soldering  
material of Claim 1.

20. (New) A solder joint formed from a lead free soldering  
material consisting essentially of Sn (tin), 10 wt.% or less Ag  
(silver), Bi (bismuth), 1 to 3 wt.% Sb (antimony), 3 wt.% or  
less Cu (copper), and 1.0 wt.% or less Ni, which is made from a  
soldering component M1 and a soldering component M2, wherein the  
Sb:Bi wt.% ratio is from 1:1.5-3.

21. (New) A solder joint of Claim 20, wherein the soldering component M1, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 3 to 12 wt.% Bi, 0.5 to 1.5 wt.% Cu and 0.05 to 0.3 wt.% Ni.

22. (New) A solder joint of Claim 20, wherein the soldering component M2, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 0.5 to 1.5 wt.% Cu, 1 to 5 wt.% Sb and 1.0 wt.% or less Ni.

23. (New) Soldering material according to Claim 1, further comprising a soldering component M1 and a soldering component M2.

24. (New) Soldering material according to Claim 23, wherein the soldering component M1, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 3 to 12 wt.% Bi, 0.5 to 1.5 wt.% Cu and 0.05 to 0.3 wt.% Ni.

25. (New) Soldering material according to Claim 23, wherein the soldering component M2, in addition to Sn as the major constituent, comprises 2 to 5 wt.% Ag, 0.5 to 1.5 wt.% Cu, 1 to 5 wt.% Sb and 1.0 wt.% or less Ni.